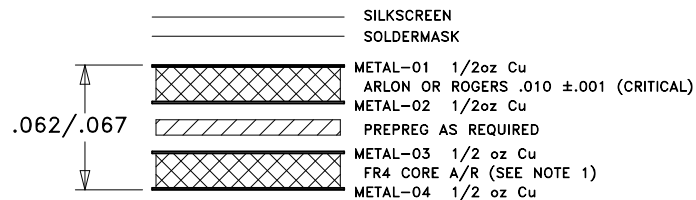


HITTITE MICROWAVE
PCB #600-00049-00-1
DRILL DRAWING



STACKUP

SIZE	QTY	SYM	PLATED	TOL
10	16	□	YES	+/-3
14	436	+	YES	+/-3
63	10	×	YES	+/-3

UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN INCHES [mm] DRAWING PRACTICES PER ASME Y14.100 INTERPRET DIMENSIONS & TOLERANCES PER ASME Y14.5-2009 TOLERANCES: .XX ± .01 .XXX ± .005 .XXXX ± .0020 ANGLES ± .5 DEG.	DRAWN BY MARTIN LYONS	DATE DRN 11/22/10
	CHECKED BY	
	ENGINEER SAVAS TOKMAK	
	THIRD ANGLE PROJECTION	
DO NOT SCALE DRAWING		

PROPRIETARY TO HITTITE MICROWAVE CORPORATION



HITTITE MICROWAVE CORPORATION
20 Alpha Road
Chelmsford, MA 01824

TITLE PCB, EVAL HMC5979A-DLP5E HMC5980A-DLP5E SINGLE-ENDED			
SIZE A	CODE ID NO. 1CN88	DWG NO. 600-00049-00	REV 1
SCALE: 1:1		WT:	SHEET: 1 OF 1

REVISION			
LTR	DESCRIPTION	DATE	APPROVED
1	ENGINEERING RELEASE	12/02/10	M.LYONS

NOTES:

UNLESS OTHERWISE SPECIFIED:

1. MATERIAL: MULTILAYER. OVERALL STACKUP AS SHOWN. TYPE ROGERS 4350 OR ARLON 25FR, HALF OUNCE COPPER BOTH SIDES. FR4 TO BE USED AS FILLER TO MEET CRITICAL OVERALL THICKNESS.
2. FINISH: GOLD PLATE PER ASTM B-488, TYPE III, CODE A, 8 TO 40 MICROINCHES, OVER NICKEL PER QQ-N-290, 100 MICROINCHES MINIMUM.
3. PLATED THRU HOLES: .001 MINIMUM WALL THICKNESS.
4. HOLE SIZES AND POSITIONS PER ARTWORK AND/OR DRILL FILE.
5. ALL HOLES TO BE LOCATED WITHIN ±.003 OF THE CENTER OF THE PAD OR OTHER TRUE POSITION.
6. FRONT TO BACK REGISTRATION ±.003 MAX.
7. BOARD WARPAGE: <.010 PER LINEAR INCH.
8. SILKSCREEN TOP SIDE ONLY WITH WHITE EPOXY INK.
9. SOLDERMASK: LPI SOLDERMASK TOP SIDE. COLOR: GREEN REGISTRATION: ±.004 MAX.
10. "SIZE" IN DRILL LEGEND IS IN MILS AND REFERS TO FINISHED HOLE SIZE.
11. MANUFACTURE PER IPC-6012 CLASS 2.

SPECIAL REQUIREMENTS:

12. CRITICAL LINE WIDTH = .016 ±.001 ON METAL-01. ADJUST PROCESS TO ACHIEVE WIDTH.

VENDOR NOTES:

13. VENDOR MAY ADD E-TEST STAMP TO PCB. VENDOR SHALL NOT ADD NAME, LOGO, DATE CODE, UL LISTING OR ANY OTHER MARKING TO ANY VISIBLE LAYER.
14. BOARDS MUST PASS VISUAL INSPECTION PER IPC-A-600 CLASS 2.